Universal Introduces Uflex to Asia Market at NEPCON South China

VISIT UNIVERSAL INSTRUMENTS on BOOTH IN65

August 29-31 | Shenzhen, China

Ultimate flexibility. Simplified automation.

Uflex™ features a revolutionary architecture that enables user-level programming and field reconfigurability to speed time to market and dramatically shorten the payback period.

Find out more

Hot bar for volume productivity.

FuzionOF™and **Flexbond™** provide a fully automated, full-process volume solution for advanced flex circuit and other hot bar applications.

Find out more about Fuzion | Find out more about Flexbond

Accuracy and throughput over the largest work area.

FuzionSC™ places a broad range of die and surface mount components and is the lowest-cost solution for multi-die flip chip, System-in-Package (SiP) and fan-out assembly.

Find out more

Value. Scalability. Performance.

AdvantisV™ combines the best in technology and performance with a low entry price and unmatched scalability.

Find out more

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Find out more about Universal Instruments at NEPCON